

Q-TECH CORPORATION

Gold Plated Leads and the Gold Embrittlement Issue

July 24, 2014

The standard lead finish on all parts manufactured or supplied by Q-Tech Corporation is Electro-Gold Plate over Electro-Nickel Plate per MIL-PRF-55310. If these parts are simply soldered to a Printed Circuit Board with lead-tin solder, gold embrittlement may ensue. To avoid this, your process must include a double solder pre-dip to remove the gold before reflowing or other solder attachment operations. We also can supply you, upon request, with leads which have been double pre-dipped with SN60/PB40 solder to remove the gold from the leads. Because many customers use various alloys for soldering (including lead-free), we have chosen to avoid offering any solder composition other than this alloy, which is also listed as a lead finish option in MIL-PRF-55310. To order "Gold Free Leads" contact your Q-Tech Regional Sales Manager and advise that you want your oscillator's leads (60/40) solder dipped when you submit your RFQ or place your purchase order. You will be provided with a quote for this process.

For further information, please reference the "Lead Free Processes and Manufacturing" article on our website, www.Q-Tech.com, and the publication MIL-STD-883 along with ANSI/J-002, -004, and -006 soldering specifications.



Charles Peot
Deputy Director of Quality Assurance
Q-Tech Corporation
Charles.Peot@Q-Tech.com
310.836.7900 extension 168